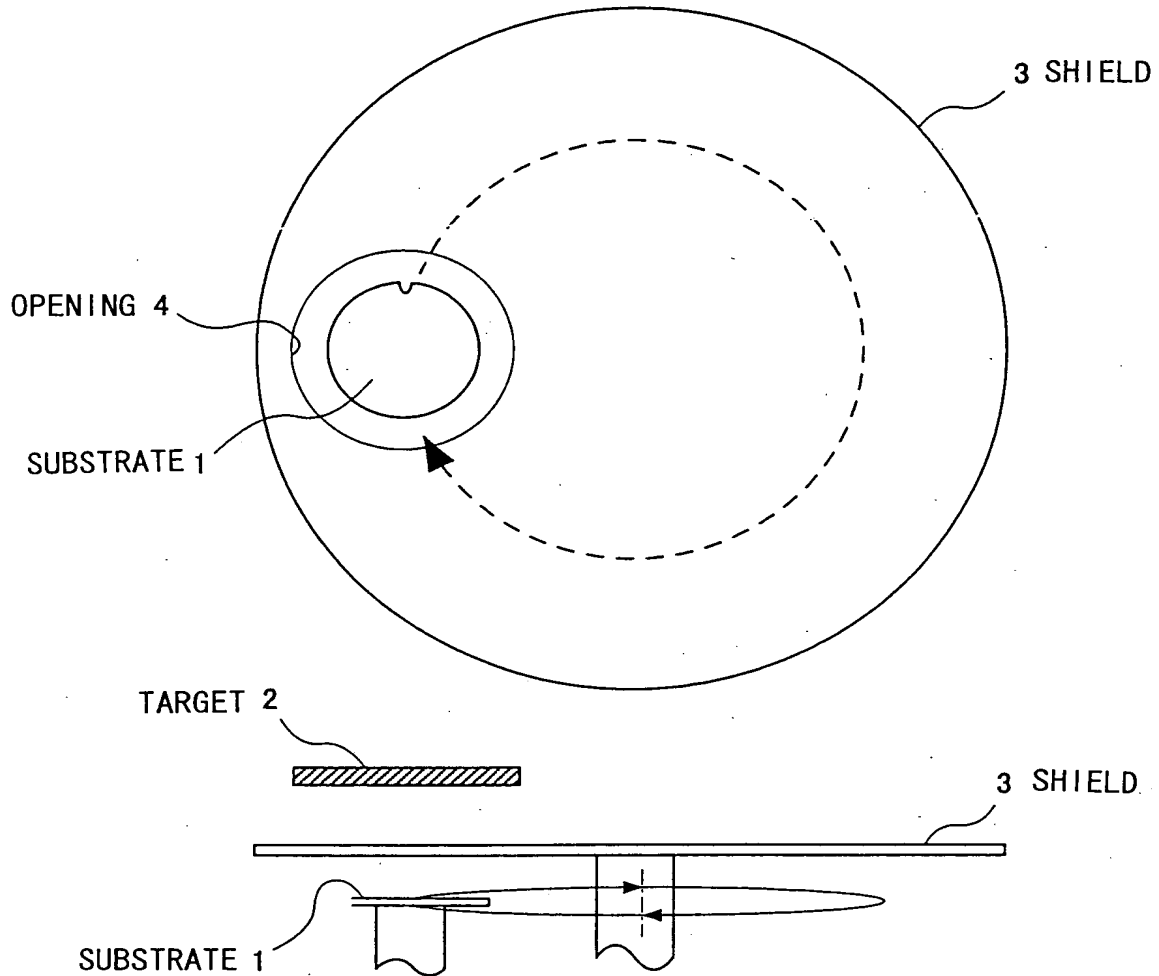


FIG. 1



TOP-67109560

FIG. 2

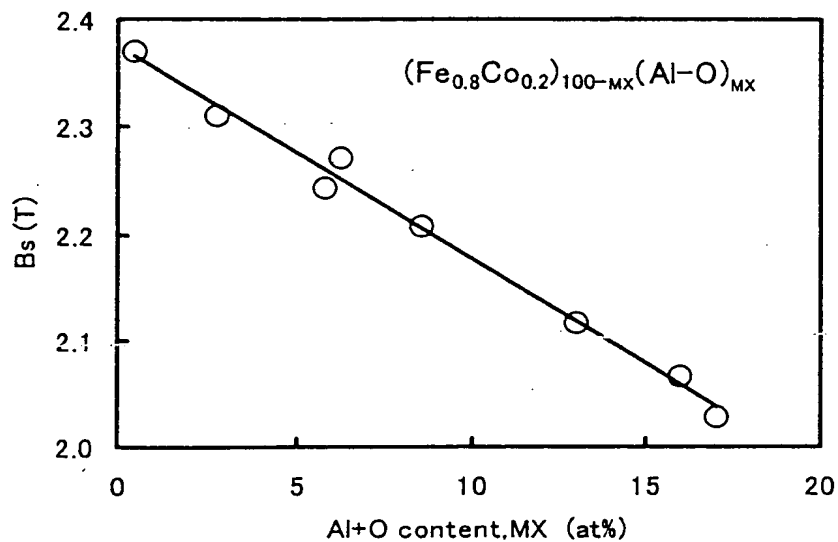


FIG. 3

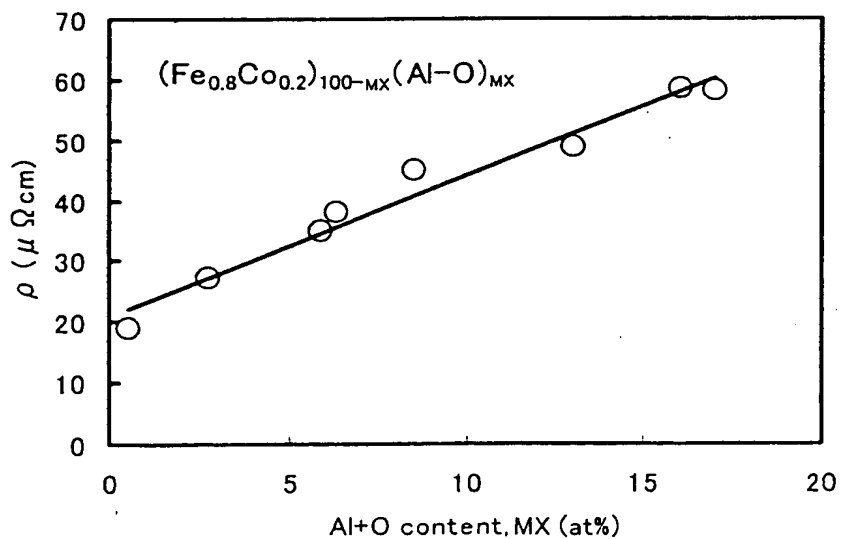
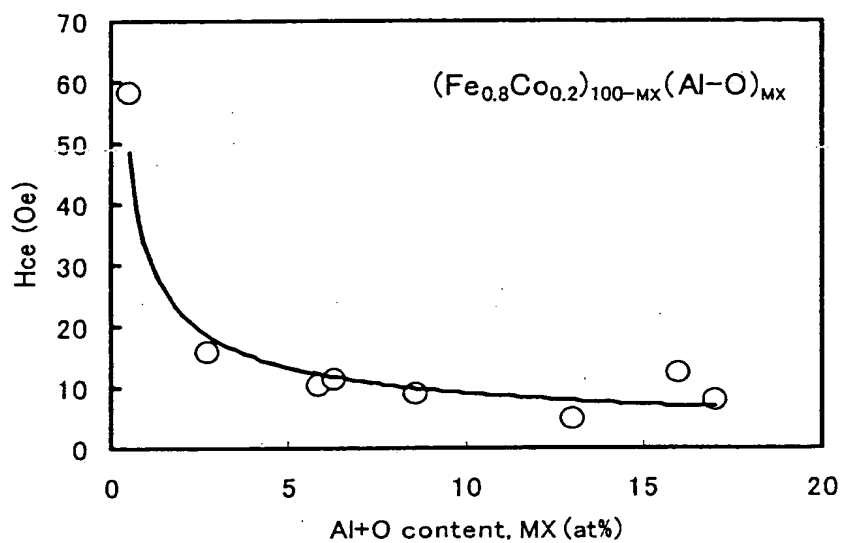


FIG. 4



FOR 60-6740360

FIG. 5A

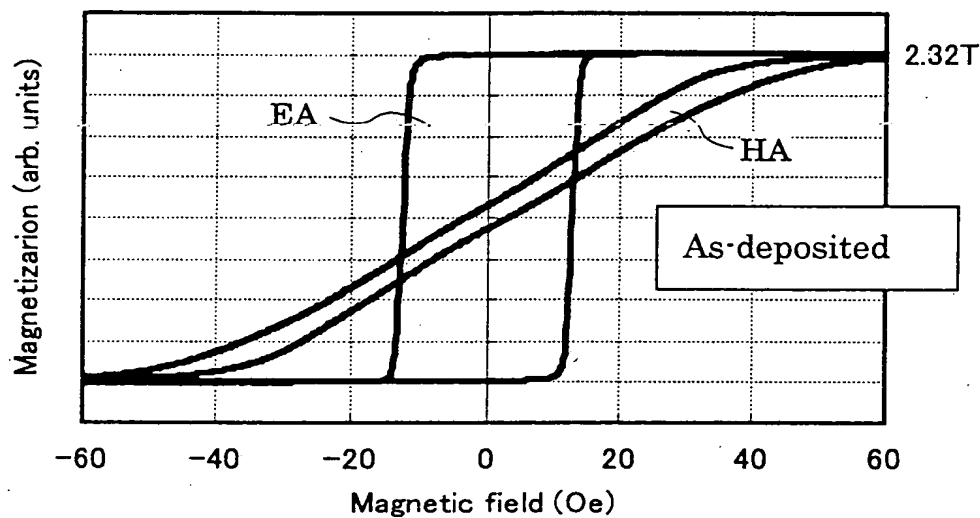


FIG. 5B

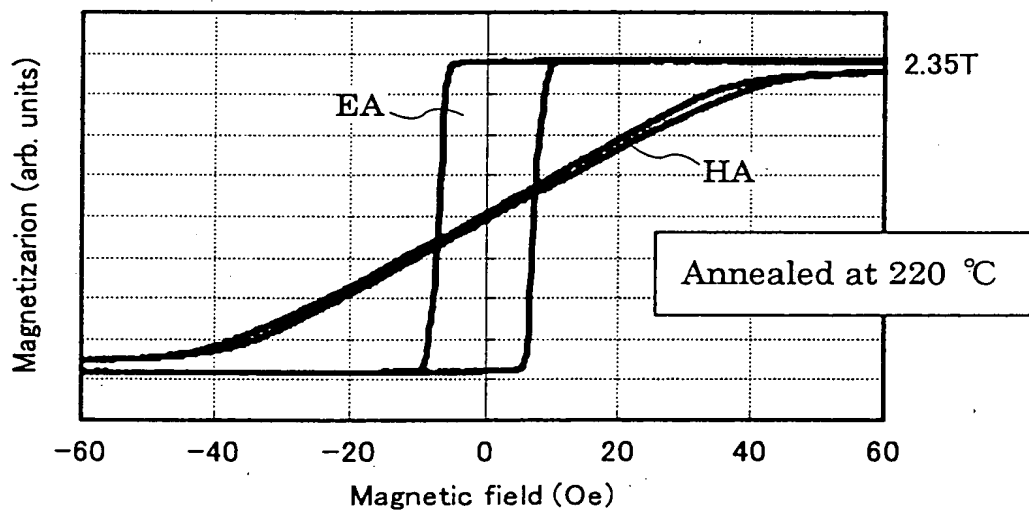
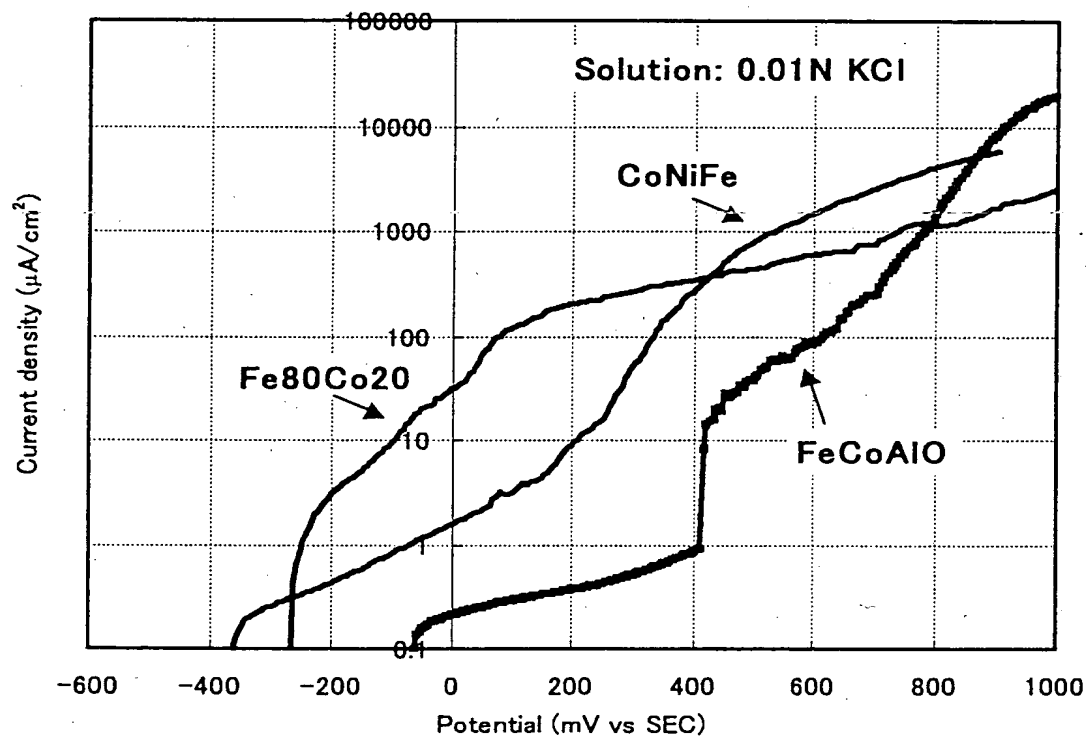


FIG. 6

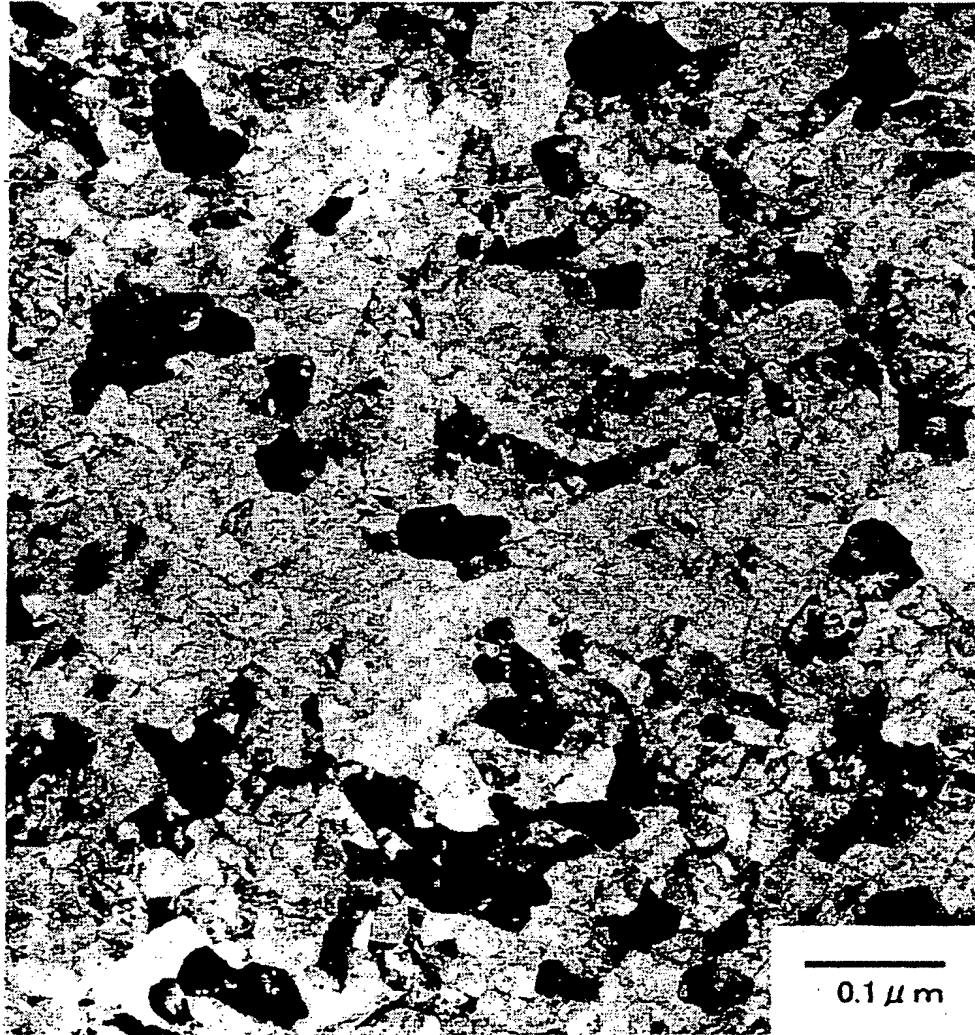
	Film structure	H _{ce} (Oe)
①	(Fe77.7Co19.5Al0.6O2.2) 0.5 μm	15
②	"	7
③	(Fe77.7Co19.5Al0.6O2.2) 0.5 μm/(Ni50Fe50) 1.6 μm	4
	"	2
④	(Ni50Fe50) 3nm/(Fe77.7Co19.5Al0.6O2.2) 0.5 μm	10
⑤	(Ni80Fe20) 3nm/(Fe77.7Co19.5Al0.6O2.2) 0.5 μm	8
⑥	(Ni80Fe20) 3nm/(Fe77.7Co19.5Al0.6O2.2) 0.5 μm/(Ni50Fe50) 1.6 μm	1

FIG. 7



101200-61109000

FIG. 8



0941.65839-07

FIG. 9A

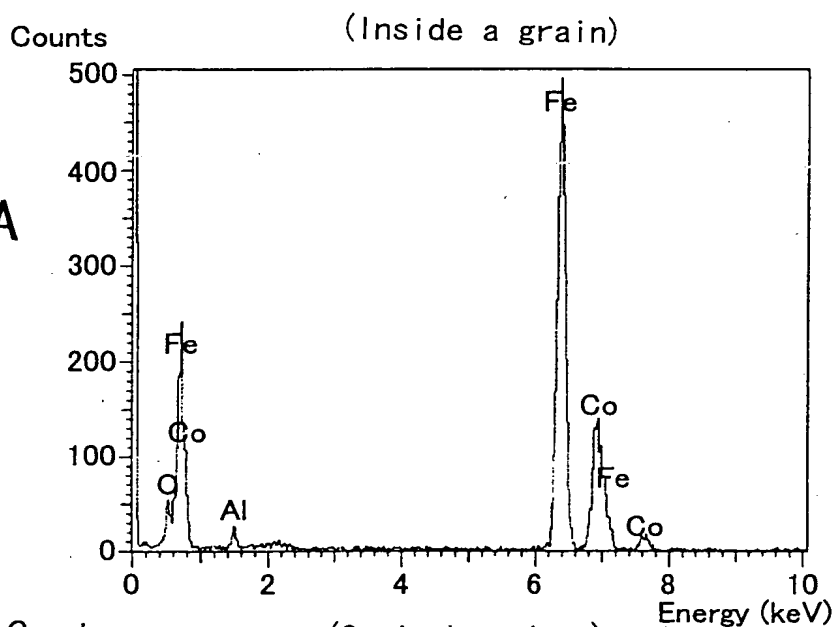


FIG. 9B

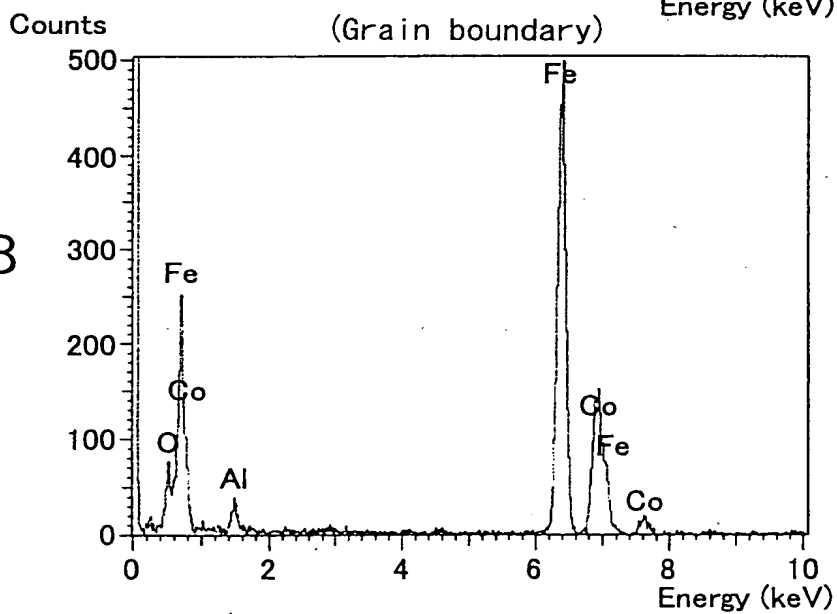
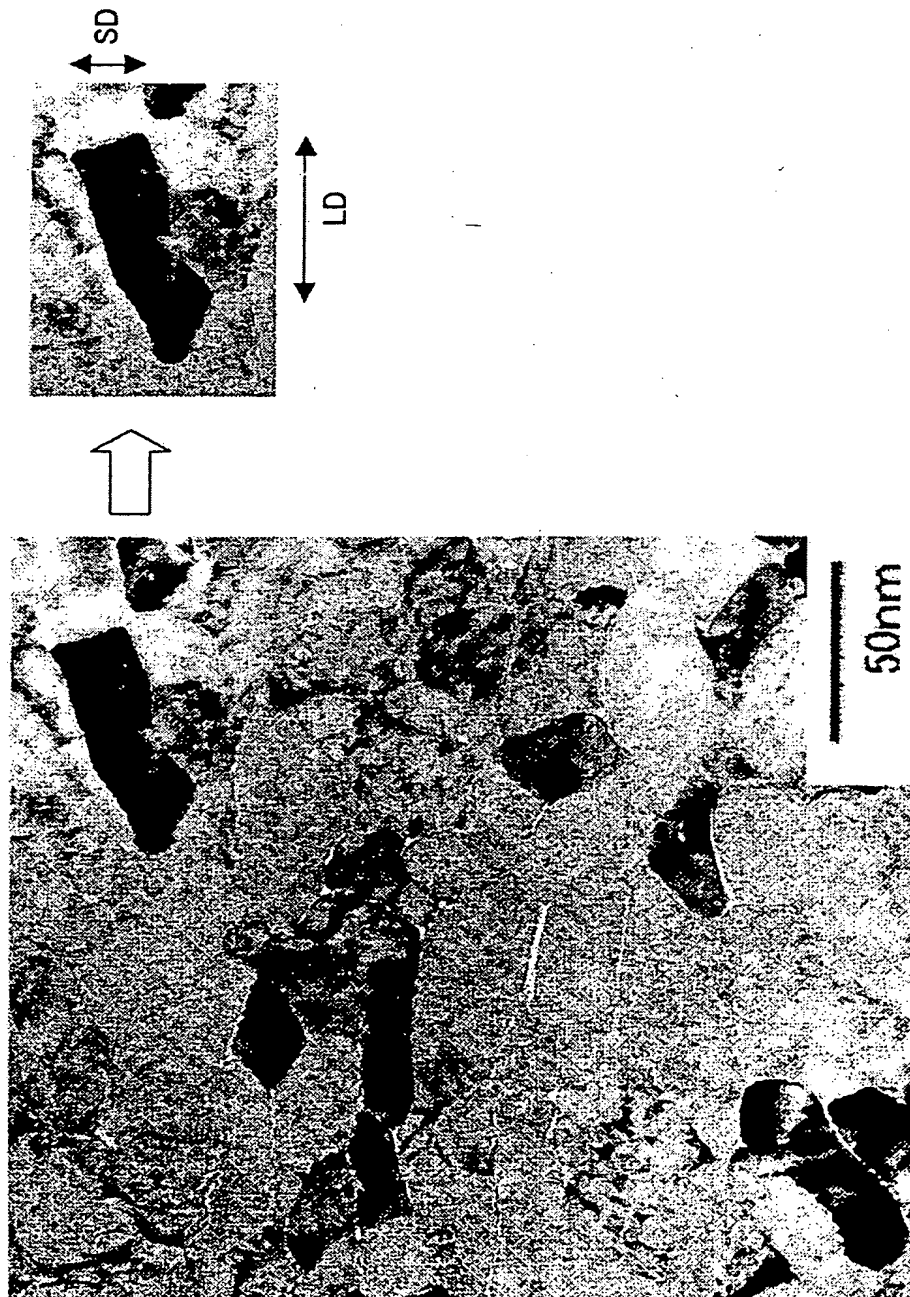


FIG. 10



101200-01105000

FIG. 11

Alloy composition (at%)			Sputtering pressure (Pa)	Residual stress σ (10^9 dyne/cm ²)	H _{kh} (Oe)
Fe	Co	Al			
71.3	18.1	2.5	0.5	-5.2	47.1
71.8	18.1	2.3	0.7	-0.9	25.5

FIG. 12

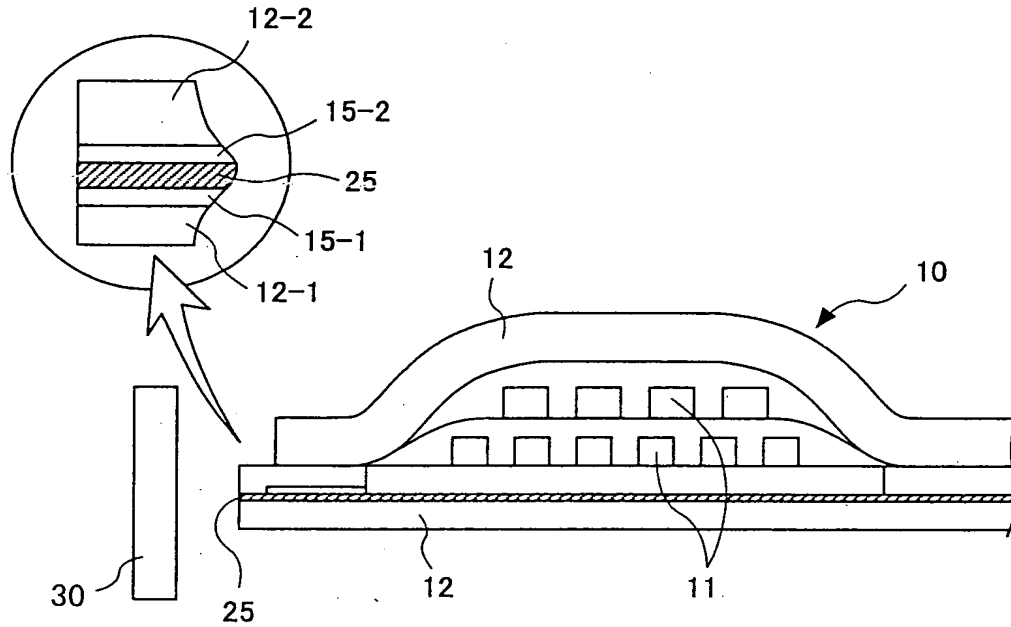
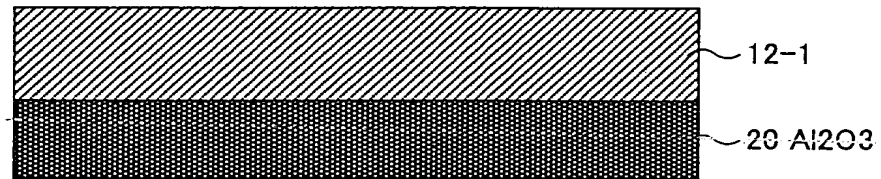


FIG. 12

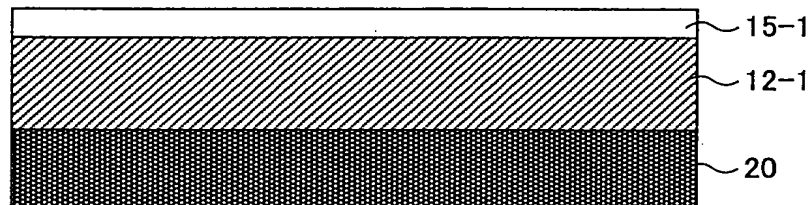
PLATING (NiFe,CoNiFe)

FIG. 13A



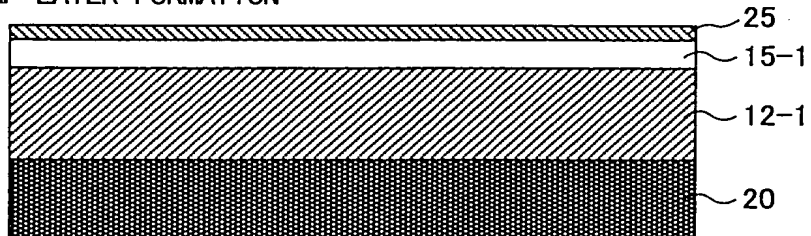
FeCoMo FILM FORMATION BY SPUTTERING

FIG. 13B



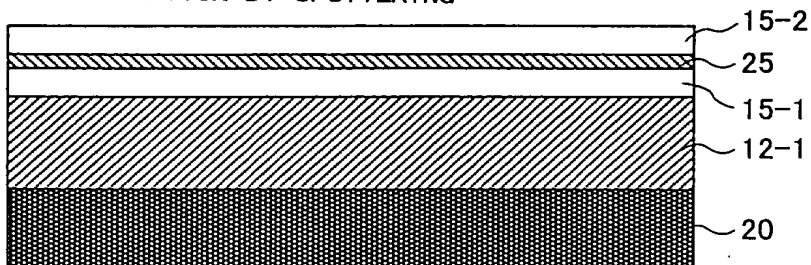
Al₂O₃ GAP LAYER FORMATION

FIG. 13C



FeCoMo FILM FORMATION BY SPUTTERING

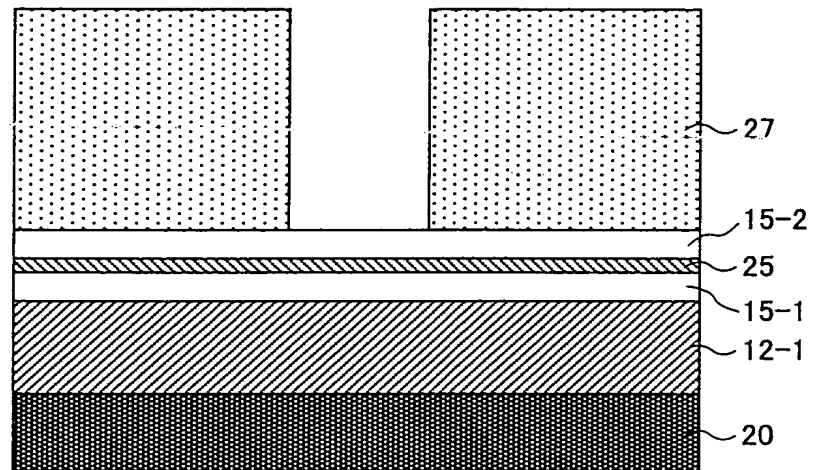
FIG. 13D



0941.65839-0000

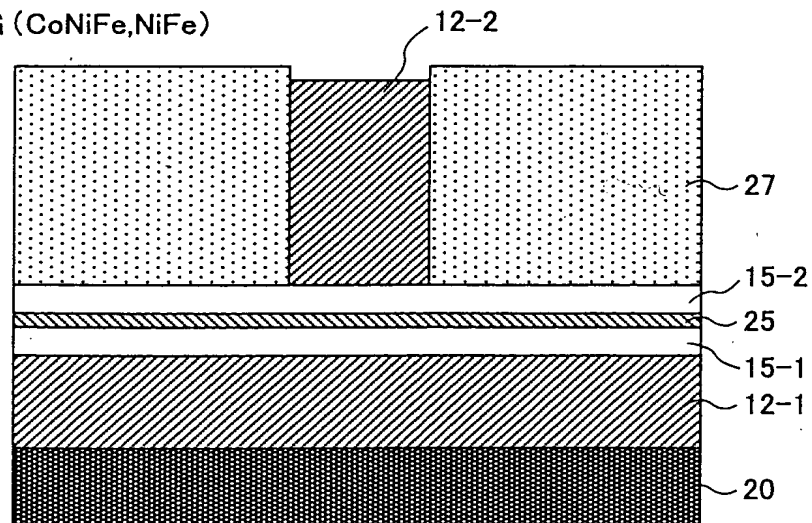
PATTERN FORMATION BY USING A RESIST

FIG. 14A



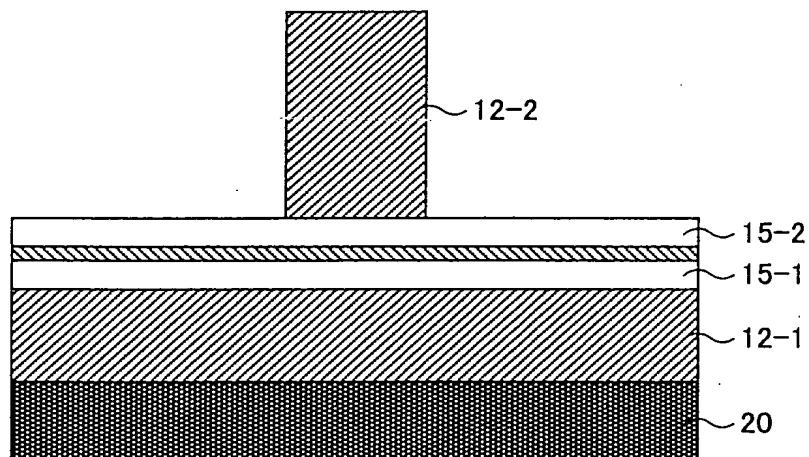
PLATING (CoNiFe, NiFe)

FIG. 14B



REMOVING THE RESIST

FIG. 15A



ETCHING : FORMING AN END-PORTION MAGNETIC POLE

FIG. 15B

